

HIGH PERFORMANCE POLYAMIDE RESIN

Zytel® HTN high performance polyamide resins feature high retention of properties upon exposure to elevated temperature, to high moisture, and to harsh chemical environments. Polymer families and grades of Zytel® HTN are tailored to optimize performance as well as processability.

Typical applications with Zytel® HTN include demanding applications in the automotive, electrical and electronics, domestic appliances, and construction industries.

Zytel® HTN510EFT NC010 is an unreinforced, toughened, heat stabilised high performance polyamide resin for injection moulding. It is also a PPA resin.

Product information

Resin Identification Part Marking Code Part Marking Code	PA6T/XT-I >PA6T/XT-I< >PPA-I<		ISO 1043 ISO 11469 SAE J1344
Rheological properties	dry/cond.		
Viscosity number	84.4/*	cm ³ /g	ISO 307, 1628
Moulding shrinkage, parallel	0.8/-	%	ISO 294-4, 2577
Moulding shrinkage, normal	0.8/-	%	ISO 294-4, 2577
Typical mechanical properties	dry/cond.		
Tensile modulus	2100/2400	MPa	ISO 527-1/-2
Tensile stress at yield, 50mm/min	67/69	MPa	ISO 527-1/-2
Tensile strain at yield, 50mm/min	6/4	%	ISO 527-1/-2
Nominal strain at break	21/-	%	ISO 527-1/-2
Charpy impact strength, 23°C	N/-	kJ/m²	ISO 179/1eU
Charpy impact strength, -30°C	N/-	kJ/m²	ISO 179/1eU
Charpy impact strength, -40°C	N/-	kJ/m²	ISO 179/1eU
Charpy notched impact strength, 23°C	90/-	kJ/m²	ISO 179/1eA
Charpy notched impact strength, -30°C	20/-	kJ/m²	ISO 179/1eA
Charpy notched impact strength, -40°C	15/-	kJ/m²	ISO 179/1eA
Poisson's ratio	0.4/0.38		
Thermal properties	dry/cond.		
Melting temperature, 10 °C/min	300/*	°C	ISO 11357-1/-3
Melting temperature, first heat	300/*	°C	ISO 11357-1/-3
Glass transition temperature, 10°C/min	140/95	°C	ISO 11357-1/-3
Temperature of deflection under load, 1.8 MPa	124/*	°C	ISO 75-1/-2
Coeff. of linear therm. expansion, parallel, -40-23°C	65/*	E-6/K	ISO 11359-1/-2
CLTE, Parallel, 23-55°C(73-130°F)	67/-	E-6/K	ASTM E 831
Coeff. of linear therm. expansion, normal, -40-23°C	71 / *	E-6/K	ISO 11359-1/-2
Coeff. of linear therm. expansion, Normal,23-55°C (73-130°F)	75/-	E-6/K	ASTM E 831

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Flammability	√ dry/c	ond.
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Burning Behav. at thickness h	HB/*	class	IEC 60695-11-10
Thickness tested	0.75/*	mm	IEC 60695-11-10
FMVSS Class	B ^[1]		ISO 3795 (FMVSS 302)
Burning rate, Thickness 1 mm	28	mm/min	ISO 3795 (FMVSS 302)
[1]: 2mm nom. thick			

Electrical properties

Volume resistivity	>1E13/>1E13	Ohm.m	IEC 62631-3-1
Electric strength	40/40	kV/mm	IEC 60243-1
Comparative tracking index	600/-		IEC 60112

dry/cond.

Physical/Other properties dry/cond.

Humidity absorption, 2mm	1.9/*	%	Sim. to ISO 62
Water absorption, 2mm	6.3/*	%	Sim. to ISO 62
Density	1120/-	kg/m³	ISO 1183

Injection

Drying Recommended	yes
Drying Temperature	100 °C
Drying Time, Dehumidified Dryer	6-8 h
Processing Moisture Content	≤0.1 %
Melt Temperature Optimum	325 °C
Min. melt temperature	320 °C
Max. melt temperature	330 °C
Mold Temperature Optimum	100 °C
Min. mould temperature	80 °C
Max. mould temperature	120 °C
Ejection temperature	242 °C

Characteristics

Processing Injection Moulding

Delivery form Pellets

Additives Release agent

Special characteristics High impact or impact modified, Heat stabilised or stable to heat, Hydrolysis

resistant

Additional information

Injection molding During molding, use proper protective equipment and adequate ventilation.

Avoid exposure to fumes and limit the hold up time and temperature of the resin in

the machine. Purge degraded resin carefully with HDPE.

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Automotive

OEM STANDARD ADDITIONAL INFORMATION

 Bosch
 N28 BN05-OX088

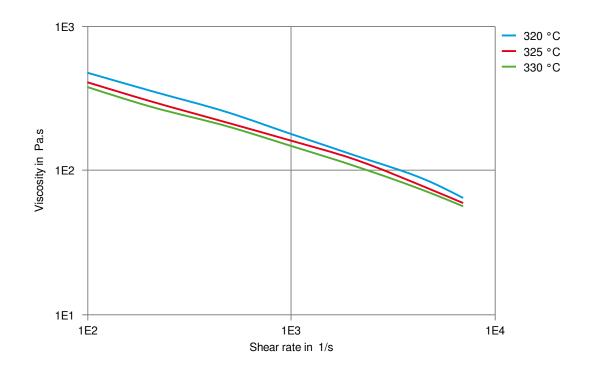
 Ford
 WSS-M98P14-A9

General Motors Natural, Special Parts Approval, See Your CE

Account Representative for Further Details.

General Motors GMW16799P-PPA-T2 Natural

Viscosity-shear rate (measured on Zytel® HTN510EFT BK010)

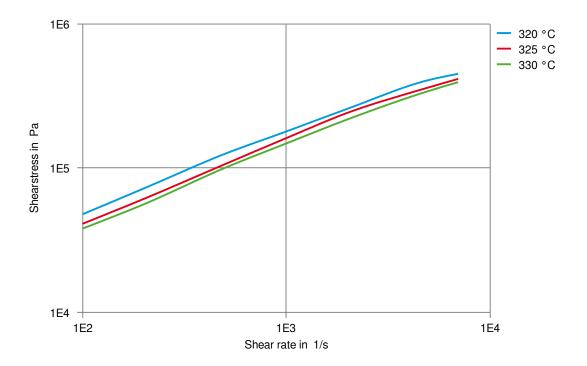


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Shearstress-shear rate (measured on Zytel® HTN510EFT BK010)

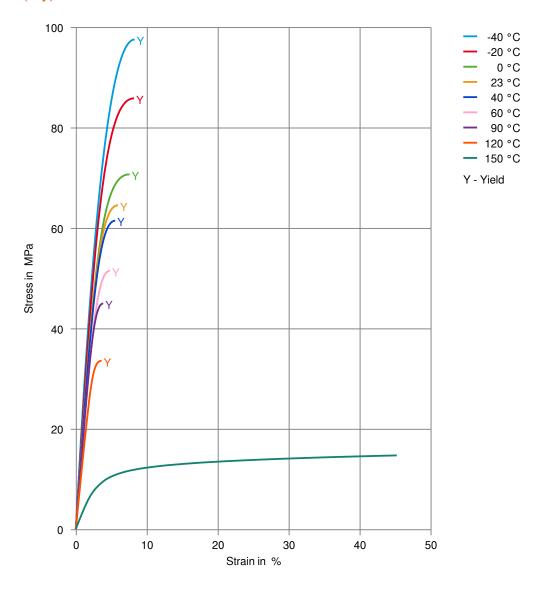


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Stress-strain (dry)

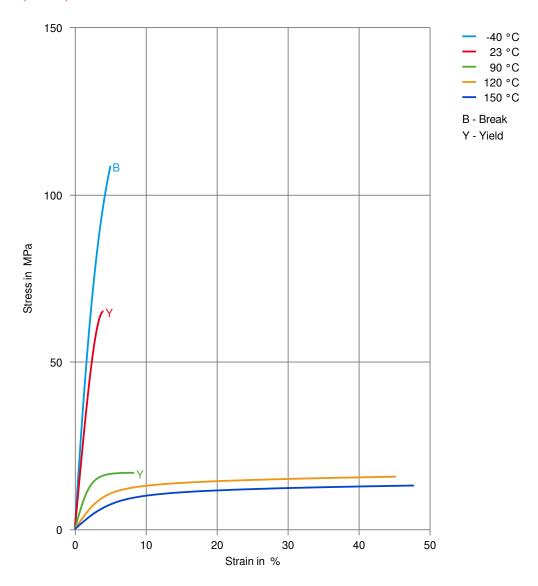


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HIGH PERFORMANCE POLYAMIDE RESIN

Stress-strain (cond.)

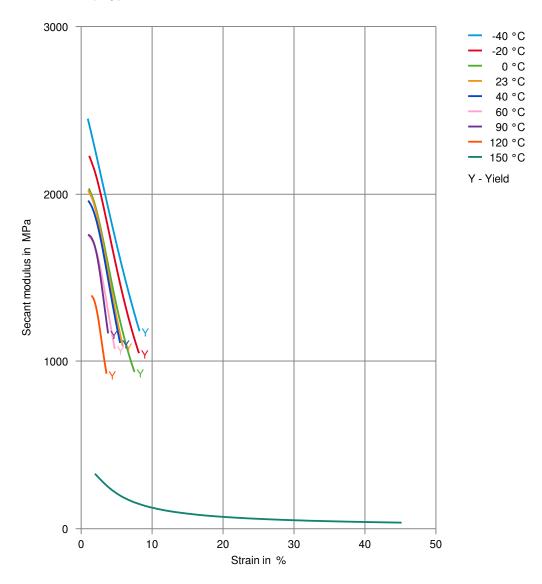


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Secant modulus-strain (dry)

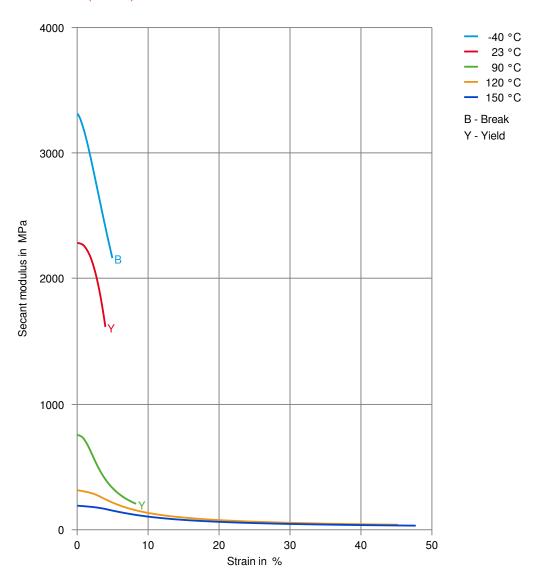


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HIGH PERFORMANCE POLYAMIDE RESIN

Secant modulus-strain (cond.)



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Revised: 2025-03-05 Source: Celanese Materials Database

NOTICE TO USERS: Values shown are based on testing of laboratory test specimens and represent data that fall within the standard range of properties for natural material. These values alone do not represent a sufficient basis for any part design and are not intended for use in establishing maximum, minimum, or ranges of values for specification purposes. Colourants or other additives may cause significant variations in data values. Properties of moulded parts can be influenced by a wide variety of factors including, but not limited to, material selection, additives, part design, processing conditions and environmental exposure. Other than those products expressly identified as medical grade (including by MT® product designation or otherwise), Celanese's products are not intended for use in medical or dental implants. Regardless of any such product designation, any determination of the suitability of a particular material and part design for any use contemplated by the users and the manner of such use is the sole responsibility of the users, who must assure themselves that the material as subsequently processed meets the needs of their particular product or use. To the best of our knowledge, the information contained in this publication is accurate; however, we do not assume any liability whatsoever for the accuracy and completeness of such information. The information contained in this publication should not be construed as a promise or guarantee of specific properties of our products. It is the sole responsibility of the users to investigate whether any existing patents are infringed by the use of the materials mentioned in this publication. Moreover, there is a need to reduce human exposure to many materials to the lowest practical limits in view of possible adverse effects. To the extent that any hazards may have been mentioned in this publication, we neither suggest nor guarantee that such hazards are the only ones that exist. We recommend that persons intending to rely on any recommendation or to use any e

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